Product Change Notification: DSNO-22VCET592

Date:

26-Jan-2026

Product Category:

Memory

Notification Subject:

CCB 7787.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 24AA1025, 24AA1026, 24AA128, 24AA256, 24AA32A, 24AA512, 24AA515, 24AA64, 24CS128, 24CS256, 24CS32, 24CS512, 24CS64, 24CSM01, 24CW1280, 24CW160, 24CW320, 24CW640, 24FC1025, 24FC1026, 24FC128, 24FC256, 24FC512, 24FC515, 24FC64, 24LC1025, 24LC1026, 24LC128, 24LC256, 24LC32A, 24LC512, 24LC515, 24LC64, 25AA1024, 25LC1024, AT24C512C, AT24CM01 and AT25M01 device families available in 8L SOIC (.150in) and 8L SOIJ (.208in) packages at MTAI assembly site.

Affected CPNs:

DSNO-22VCET592_Affected_CPN_01262026.pdf
DSNO-22VCET592_Affected_CPN_01262026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 24AA1025, 24AA1026, 24AA128, 24AA256, 24AA32A, 24AA512, 24AA515, 24AA64, 24CS128, 24CS256, 24CS32, 24CS512, 24CS64, 24CSM01, 24CW1280, 24CW160, 24CW320, 24CW640, 24FC1025, 24FC1026, 24FC128, 24FC256, 24FC512, 24FC515, 24FC64, 24LC1025, 24LC1026, 24LC128, 24LC256, 24LC32A, 24LC512, 24LC515, 24LC64, 25AA1024, 25LC1024, AT24C512C, AT24CM01 and AT25M01 device families available in 8L SOIC (.150in) and 8L SOIJ (.208in) packages at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free) 8390A (PFAS-free)	QMI519 (PFAS-free) 8390A (PFAS-free)	No
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material at MTAI assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 15 April 2026 (date code: 2616)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	January 2026					>	**April 2026**				
Work Week	01	02	03	04	05		14	15	16	17	18
Qual Report Availability					x						
Final PCN Issue Date					x						
Estimated Implementation Date									x		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: January 26, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-22VCET592_Qualification_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

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